

Vishay Siliconix

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)			
30	0.0033 at V _{GS} = 10 V	30	37 nC			
30	0.0041 at V _{GS} = 4.5 V	26.3	37 110			

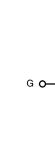
FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested

ROHS COMPLIANT HALOGEN FREE Available

APPLICATIONS

- Low-Side DC/DC Conversion
 - Notebook
 - Gaming



N-Channel MOSFET

SO-8 S 1 8 D S 2 7 D S 3 6 D Top View

Ordering Information: Si4626ADY-T1-E3 (Lead (Pb)-free)

Si4626ADY-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter Drain-Source Voltage Gate-Source Voltage		Symbol	Limit	Unit	
		V _{DS}	30 ± 20	v	
		V_{GS}			
	T _C = 25 °C		30		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	l _a	22.6		
Continuous Brain Current (1) = 100 O)	T _A = 25 °C	'D	21.5 ^{b, c}		
	T _A = 70 °C		17.1 ^{b, c}		
Pulsed Drain Current		I _{DM}	70	A	
Continuous Source-Drain Diode Current	T _C = 25 °C	1.	5.4		
Continuous Source-Drain Diode Current	T _A = 25 °C	ls –	2.7 ^{b, c}		
Single Pulse Avalanche Current	1 - 0.1 mH	I _{AS}	40		
Avalanche Energy L = 0.1 mH		E _{AS}	80	mJ	
	T _C = 25 °C		6.0		
Maximum Power Dissipation	T _C = 70 °C	P _D	3.3	١٨/	
Maximum Power Dissipation	T _A = 25 °C	Т В	3.0 ^{b, c}	V A	
	T _A = 70 °C		1.9 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R_{thJA}	33	42	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	16	21	O/ V V		

Notes:

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 85 $^{\circ}\text{C/W}.$

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	30			٧	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J. 050A		37		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- I _D = 250 μA		- 7.3			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1.2		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zava Cata Valtaga Duais Courset	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			1	μΑ	
Zero Gate Voltage Drain Current					10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
		V _{GS} = 10 V, I _D = 15 A		0.0026	0.0033	_	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 10 A		0.0032	0.0041	1 Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		85		S	
Dynamic ^b					l		
Input Capacitance	C _{iss}			5370			
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		690		pF	
Reverse Transfer Capacitance	C _{rss}			330			
•		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A		82	125		
Total Gate Charge	Q _g			37	56		
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		12.6			
Gate-Drain Charge	Q _{gd}			9.8			
Gate Resistance	R_{g}	f = 1 MHz	0.2	0.95	1.9	Ω	
Turn-On Delay Time	t _{d(on)}			44	70		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_L = 3 \Omega$		21	35	- - -	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		45	70		
Fall Time	t _f			18	30		
Turn-On Delay Time	t _{d(on)}			15	30	ns	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_L = 3 \Omega$		10	20	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		43	70		
Fall Time	t _f			8	15		
Drain-Source Body Diode Characteristi	cs						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			5.4		
Pulse Diode Forward Current ^a	I _{SM}				70	A	
Body Diode Voltage	V _{SD}	I _S = 2.7 A		0.74	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			38	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1		36	60	nC	
Reverse Recovery Fall Time	t _a	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		20			
Reverse Recovery Rise Time	t _b			18		ns	

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

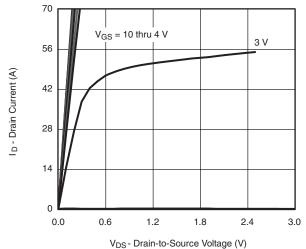
a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %

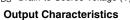
b. Guaranteed by design, not subject to production testing.

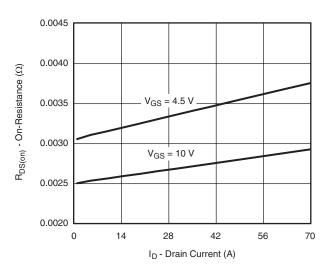


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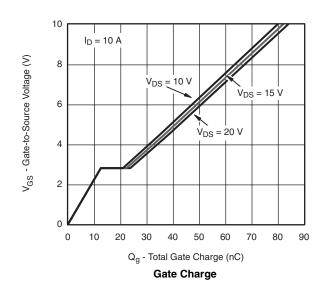
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

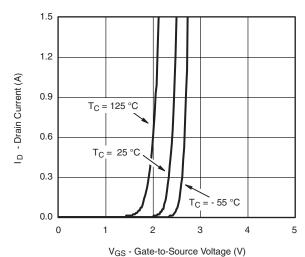




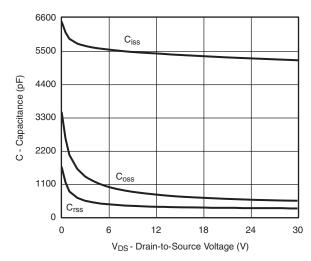


On-Resistance vs. Drain Current and Gate Voltage

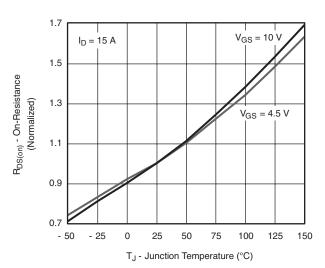




Transfer Characteristics



Capacitance

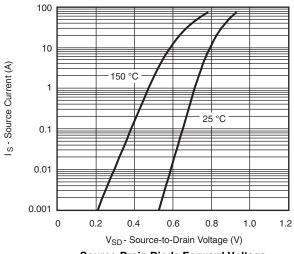


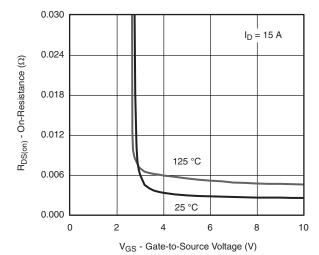
On-Resistance vs. Junction Temperature

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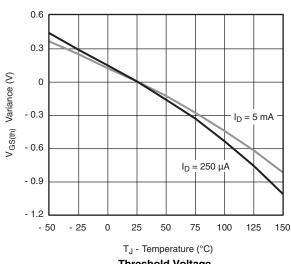
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

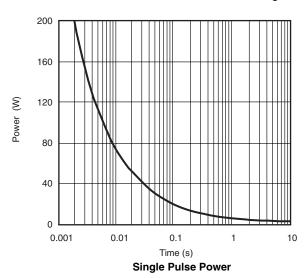




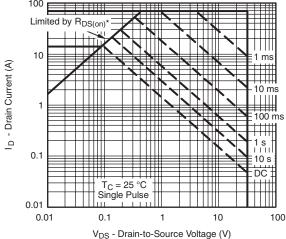
Source-Drain Diode Forward Voltage











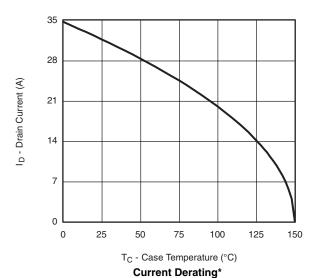
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

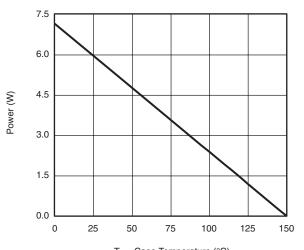
Safe Operating Area, Junction-to-Ambient



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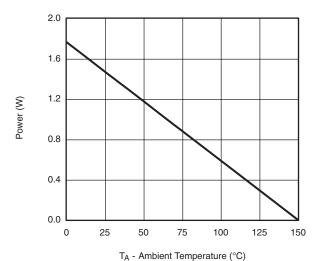
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





T_C - Case Temperature (°C)

Power Derating, Junction-to-Foot



Power, Junction-to-Ambient

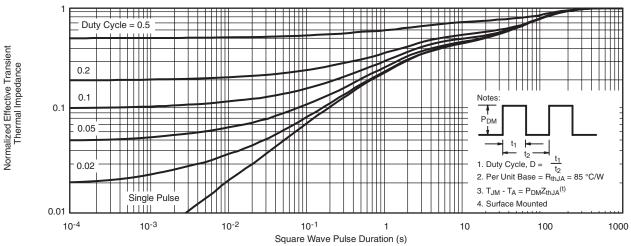
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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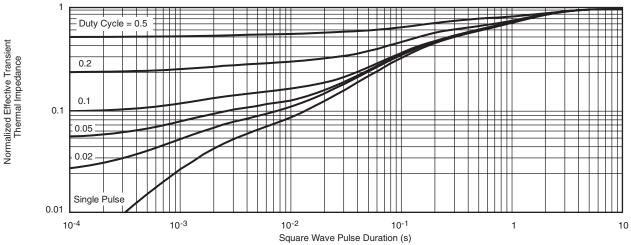
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?69937.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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